

N-Channel 100-V (D-S) MOSFET

PRODUCT SUMMARY				
V _{(BR)DSS} (V)	$r_{DS(on)}(\Omega)$	I _D (A)		
100	0.010 at V _{GS} = 10 V	50		

FEATURES

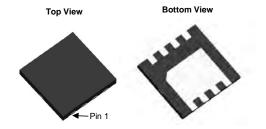
- TrenchFET® Power MOSFET
- 175 °C Junction Temperature
- Low Thermal Resistance Package
- 100 % R_g Tested

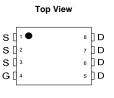


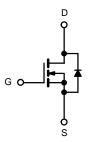
APPLICATIONS

• Isolated DC/DC Converters

DFN 3x3 EP







N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T _C = 25 °C, unless otherwise noted					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	100	V		
Gate-Source Voltage		V _{GS}	± 20	7 v	
Continuous Drain Current (T _{.1} = 175 °C)	T _C = 25 °C	I-	50		
Continuous Drain Current (1, = 175 °C)	T _C = 125 °C	I _D	45	A	
Pulsed Drain Current		I _{DM}	60		
Avalanche Current	L = 0.1 mH	I _{AS}	51		
Single Pulse Avalanche Energy ^b	L = 0.1 IIII1	E _{AS}	60	mJ	
Mariana Barra Biariantiah	T _C = 25 °C	В	355 ^c	10/	
Maximum Power Dissipation ^b	T _A = 25 °C ^d	P_{D}	3.35	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Limit	Unit	
Junction-to-Ambient	PCB Mount (TO-263) ^d	R _{thJA}	40	°C/W	
Junction-to-Case (Drain)		R _{thJC}	0.4	C/VV	

Notes:

- a. Package limited.
- b. Duty cycle \leq 1 %.
- c. See SOA curve for voltage derating.
- d. When Mounted on 1" square PCB (FR-4 material).



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	urce Breakdown Voltage V _{(BR)DSS} V _{DS}		100			V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2		4	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V V _{DS} = 100 V, V _{GS} = 0 V, T _J = 125 °C		1			
Zero Gate Voltage Drain Current					50	μA	
		V _{DS} = 100 V, V _{GS} = 0 V, T _J = 175 °C	V, V _{GS} = 0 V, T _J = 175 °C 25		250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
		V _{GS} = 10 V, I _D = 30 A		0.010		Ω	
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = 10 V, I _D = 30 A, T _J = 125 °C		0.013			
		V _{GS} = 10 V, I _D = 30 A, T _J = 175 °C		0.027			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 30 A	25			S	
Dynamic ^b	•						
Input Capacitance	C _{iss}			3200		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		410			
Reverse Transfer Capacitance	C _{rss}			210			
Total Gate Charge ^c	Q_g			90	130		
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 58 \text{ A}$		23		nC	
Gate-Drain Charge ^c	Q_{gd}			34			
Gate Resistance	R _g	0.5		1.3	3.1	Ω	
Turn-On Delay Time ^c	t _{d(on)}			24	35		
Rise Time ^c	t _r	$V_{DD} = 100 \text{ V}, R_{L} = 1.5 \Omega$		220	330	- ns	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 58 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5$		45	70		
Fall Time ^c	t _f	Ω		200	300		
Source-Drain Diode Ratings and Cha	aracteristics 7	√ _C = 25 °C ^b					
Continuous Current	Is				58	^	
Pulsed Current	I _{SM}				110	Α	
Forward Voltage ^a	V _{SD}	I _F = 58 A, V _{GS} = 0 V		1.0	1.5	V	
Reverse Recovery Time	t _{rr}			130	200	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 30 A, di/dt = 100 A/μs		8	12	Α	
Reverse Recovery Charge	Q _{rr}			0.52	1.2	иC	

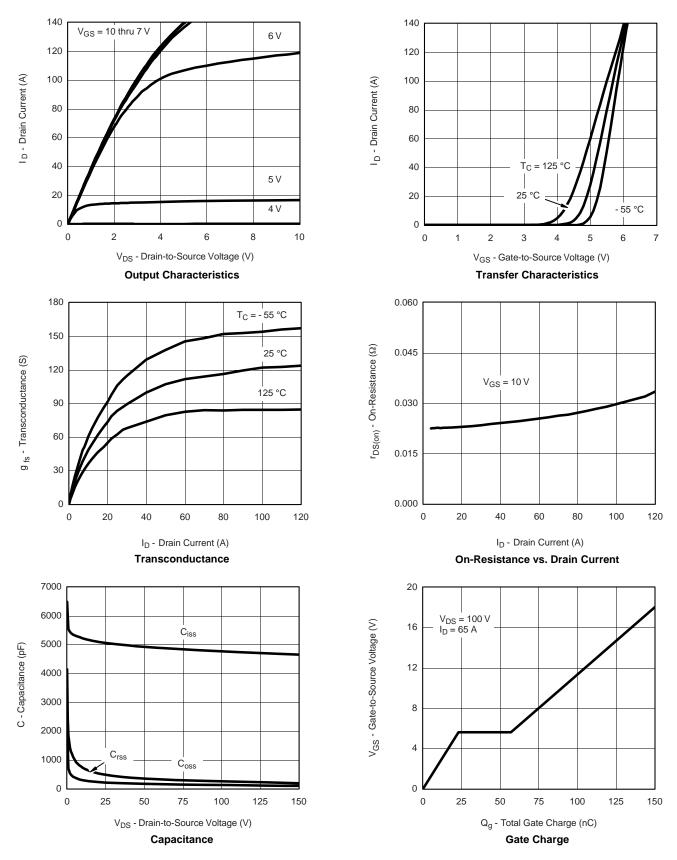
Notes

- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

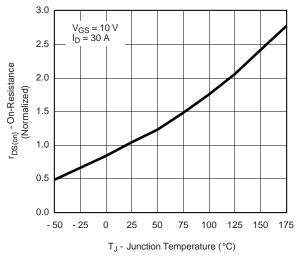


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

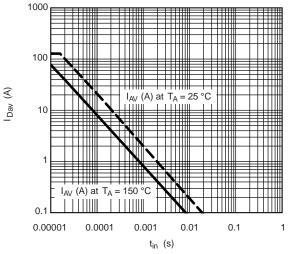




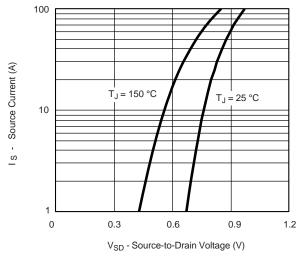
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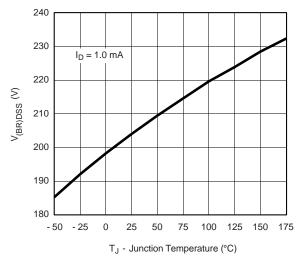
On-Resistance vs. Junction Temperature



Avalanche Current vs. Time



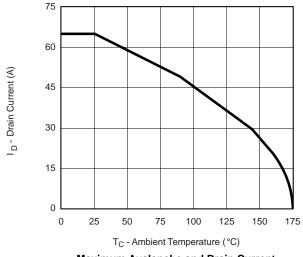
Source-Drain Diode Forward Voltage



Drain Source Breakdown vs. Junction Temperature



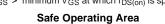
THERMAL RATINGS

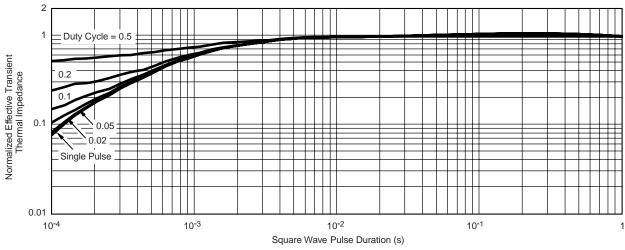


r_{DS(on)} Limited 10 µs 100 I_D - Drain Current (A) 10 T_C = 25 °C 10 ms 100 ms DC Single Pulse 0.1 0.1 100 1000 10 V_{DS} - Drain-to-Source Voltage (V) * V_{GS} > minimum V_{GS} at which $r_{DS(on)}$ is specified

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Maximum Avalanche and Drain Current vs. Case Temperature



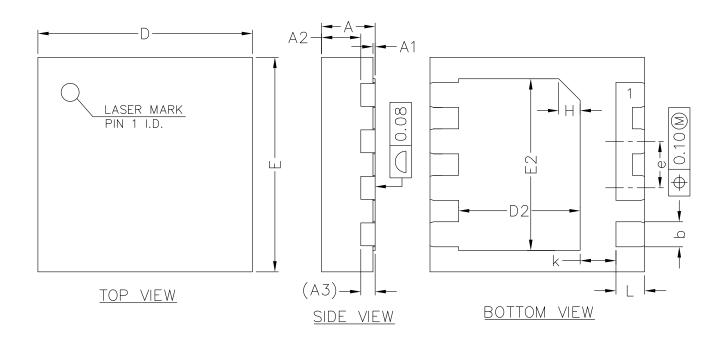


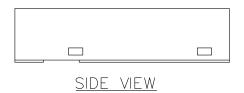
Normalized Thermal Transient Impedance, Junction-to-Case

服务热线:400-655-8788

5







COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX	
А	0.70	0.75	0.80	
A1	0.00	0.02	0.05	
A2	0.50	0.55	0.60	
А3	0.20REF			
Ь	0.30	0.35	0.40	
D	2.90	3.00	3.10	
E	2.90	3.00	3.10	
D2	1.60	1.70	1.80	
E2	2.30	2.40	2.50	
е	0.55	0.65	0.75	
K	0.40	0.50	0.60	
L	0.35	0.40	0.45	



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